

# FMW60N105F7

## N-Channel eMOS F7 Power MOSFET

600 V, 31.5 A, 105 mΩ

**FASTER**  
SEMICONDUCTOR

### Description

The 600V eMOS F7 is a fast recovery type MOSFET using E7 technology. eMOS F7 is an advanced Faster Semiconductor's Super Junction MOSFET family by utilizing charge balance technology for excellent low on-resistance and gate charge. It combines the benefits of a fast switching performance with ease of usage and robustness. Additionally, we offer low reverse recovery time( $t_r$ ) and reverse recovery charge( $Q_{rr}$ ). Thus, 600V eMOS F7 is very suitable for the bridge structure topology, especially for resonant converters (LLC, PSFB, etc.).

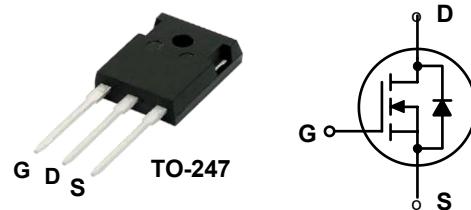
### Applications

- Soft Switching Topologies
- Telecom and Server Power Supplies
- EV Charger and Industrial Power Supplies

### Features

$BV_{DSS} @ T_{J,max}$	$I_D$	$R_{DS(on),max}$	$Q_{g,typ}$
650 V	31.5 A	105 mΩ	57.7 nC

- Reduced Switching & Conduction Losses
- Fast Recovery Body-Diode
- Lower Gate Resistance
- 100% Avalanche Tested
- Pb-free and RoHS Compliant



### Absolute Maximum Ratings ( $T_C = 25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter		Value	Unit
$V_{DSS}$	Drain to Source Voltage		600	V
$V_{GSS}$	Gate to Source Voltage		$\pm 30$	V
$I_D$	Drain Current	Continuous ( $T_C = 25^\circ\text{C}$ )	31.5	A
		Continuous ( $T_C = 100^\circ\text{C}$ )	19.9	
$I_{DM}$	Drain Current	Pulsed (Note1)	94.5	A
$E_{AS}$	Single Pulsed Avalanche Energy		187	mJ
$I_{AS}$	Avalanche Current		5.4	A
$E_{AR}$	Repetitive Avalanche Energy		2.6	mJ
$dv/dt$	MOSFET $dv/dt$		100	V/ns
	Peak Diode Recovery $dv/dt$	(Note3)	50	
$P_D$	Power Dissipation	( $T_C = 25^\circ\text{C}$ )	260	W
		Derate Above $25^\circ\text{C}$	2.08	W/ $^\circ\text{C}$
$T_J, T_{STG}$	Operating and Storage Temperature Range		-55 to 150	$^\circ\text{C}$
$T_L$	Maximum Lead Temperature for Soldering, 1/8" from Case for 10 Seconds		260	$^\circ\text{C}$

### Thermal Characteristics

Symbol	Parameter	Value	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max.	0.48	$^\circ\text{C}/\text{W}$
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient, Max.	62.5	

**Package Marking and Ordering Information**

Part Number	Top Marking	Package	Packing Method	Quantity
FMW60N105F7	FMW60N105F7	TO-247	Tube	50 units

**Electrical Characteristics** ( $T_C = 25^\circ\text{C}$  unless otherwise noted)

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
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**Off Characteristics**

BV <sub>DSS</sub>	Drain to Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 1 \text{ mA}$	600			V
		$V_{GS} = 0 \text{ V}, I_D = 1 \text{ mA}, T_J = 150^\circ\text{C}$	650			
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	$V_{DS} = 600 \text{ V}, V_{GS} = 0 \text{ V}$			10	\mu\text{A}
		$V_{DS} = 480 \text{ V}, V_{GS} = 0 \text{ V}, T_J = 125^\circ\text{C}$		60		
I <sub>GSS</sub>	Gate-Source Leakage Current	$V_{GS} = \pm 30 \text{ V}, V_{DS} = 0 \text{ V}$			$\pm 100$	nA

**On Characteristics**

$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_D = 2.1 \text{ mA}$	3.0		5.0	V
R <sub>DS(on)</sub>	Static Drain to Source On Resistance	$V_{GS} = 10 \text{ V}, I_D = 15.3 \text{ A}$		89	105	m\Omega

**Dynamic Characteristics**

C <sub>iss</sub>	Input Capacitance	$V_{DS} = 400 \text{ V}, V_{GS} = 0 \text{ V}, f = 250 \text{ kHz}$		2160		pF
C <sub>oss</sub>	Output Capacitance		55			pF
C <sub>o(tr)</sub>	Time Related Output Capacitance	$V_{DS} = 0 \text{ V to } 400 \text{ V}, V_{GS} = 0 \text{ V}$		630		pF
C <sub>o(er)</sub>	Energy Related Output Capacitance		92.3			pF
Q <sub>g(tot)</sub>	Total Gate Charge at 10 V	$V_{DS} = 400 \text{ V}, I_D = 15.3 \text{ A}, V_{GS} = 10 \text{ V}$		57.7		nC
Q <sub>gs</sub>	Gate to Source Charge		14			nC
Q <sub>gd</sub>	Gate to Drain "Miller" Charge		29.3			nC
R <sub>G</sub>	Gate Resistance	f = 1 MHz		1.1		\Omega

**Switching Characteristics**

t <sub>d(on)</sub>	Turn-On Delay Time	$V_{DS} = 400 \text{ V}, I_D = 15.3 \text{ A}, V_{GS} = 10 \text{ V}, R_G = 10 \Omega$ See Figure 13		23		ns
t <sub>r</sub>	Turn-On Rise Time			12		ns
t <sub>d(off)</sub>	Turn-Off Delay Time			80		ns
t <sub>f</sub>	Turn-Off Fall Time			9		ns

**Source-Drain Diode Characteristics**

I <sub>S</sub>	Maximum Continuous Diode Forward Current			31.5	A
I <sub>SM</sub>	Maximum Pulsed Diode Forward Current			94.5	A
V <sub>SD</sub>	Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_{SD} = 15.3 \text{ A}$		1.2	V
t <sub>rr</sub>	Reverse Recovery Time	$V_{DD} = 400 \text{ V}, I_{SD} = 15.3 \text{ A}, dI_F/dt = 100 \text{ A}/\mu\text{s}$		139	ns
Q <sub>rr</sub>	Reverse Recovery Charge			0.91	\mu C

**Notes:**

1. Repetitive rating: pulse-width limited by maximum junction temperature.
2. I<sub>AS</sub> = 5.4 A, R<sub>G</sub> = 25 \Omega, starting T<sub>J</sub> = 25°C.
3. I<sub>SD</sub> \leq 15.3 A, di/dt \leq 100 A/\mu s, V<sub>DD</sub> \leq 400 V, starting T<sub>J</sub> = 25°C.

## Typical Performance Characteristics

Figure 1. On-Region Characteristics

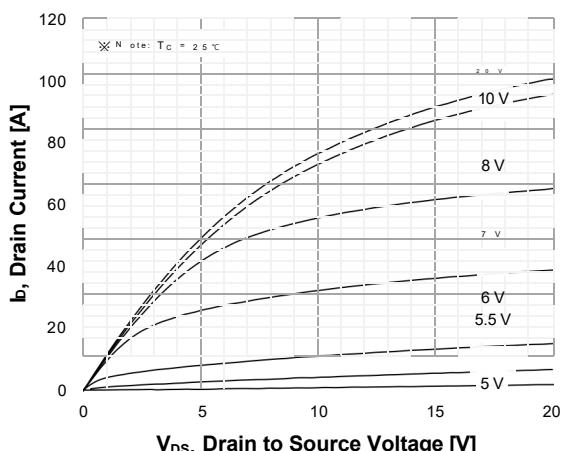


Figure 2. Transfer Characteristics

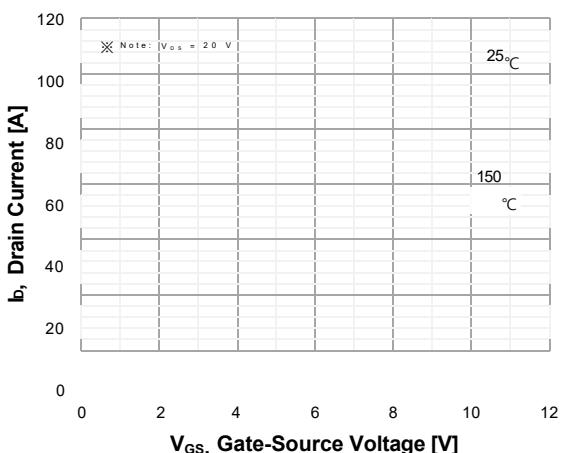


Figure 3. On-Resistance Characteristics vs. Drain Current and Gate Voltage

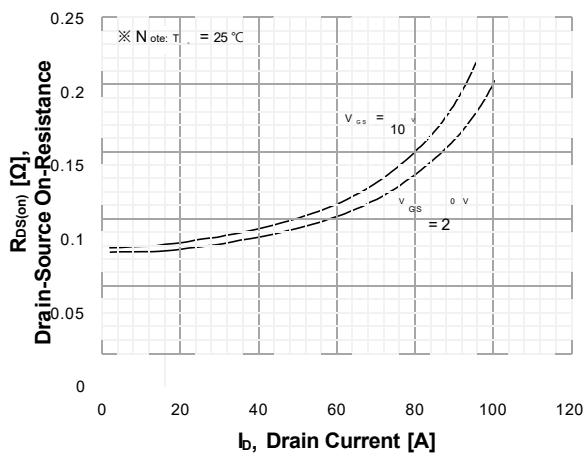


Figure 4. Diode Forward Voltage Characteristics vs. Source-Drain Current and Temperature

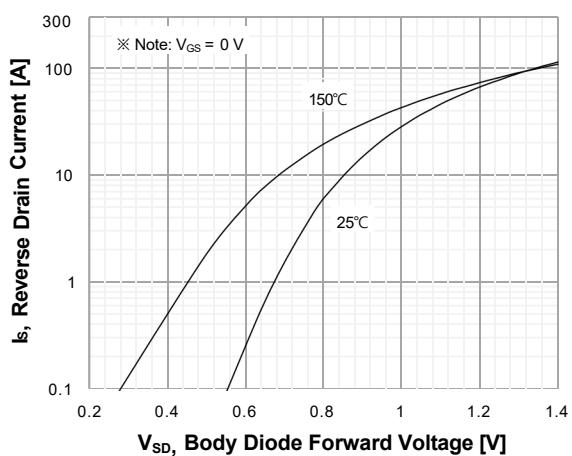


Figure 5. Capacitance Characteristics

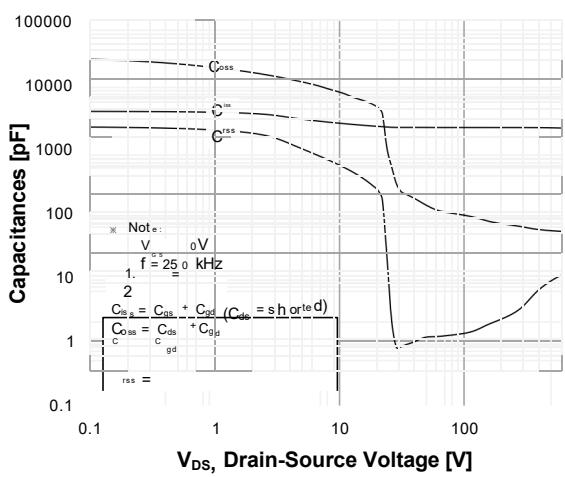
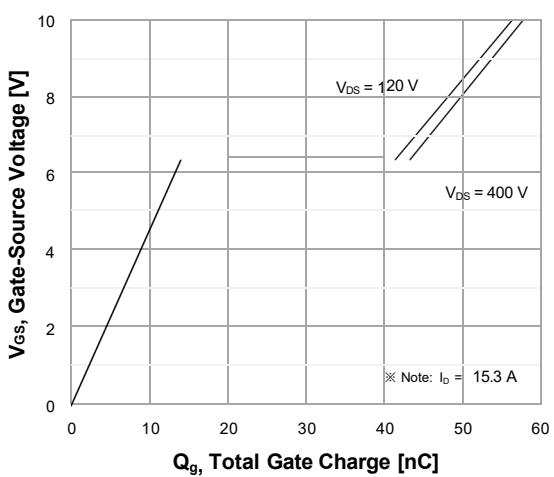
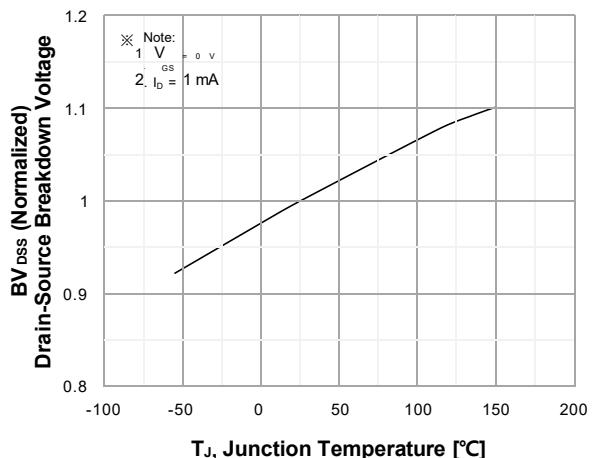


Figure 6. Gate Charge Characteristics

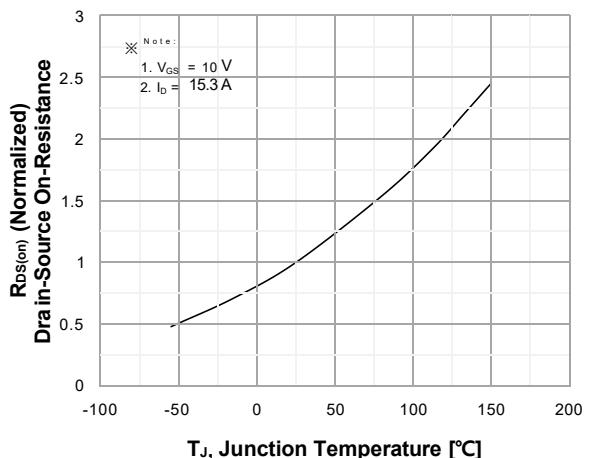


### Typical Performance Characteristics

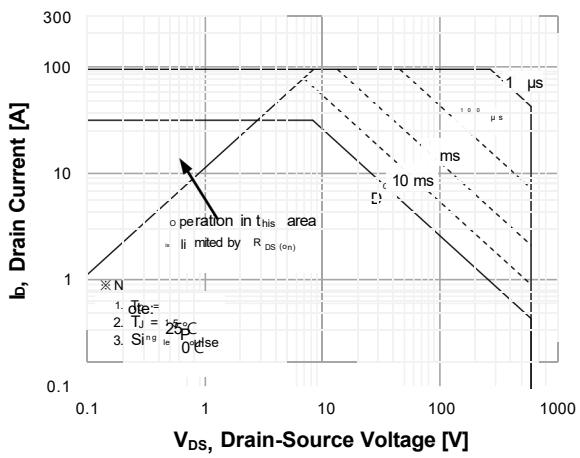
**Figure 7. Breakdown Voltage Characteristics vs. Temperature**



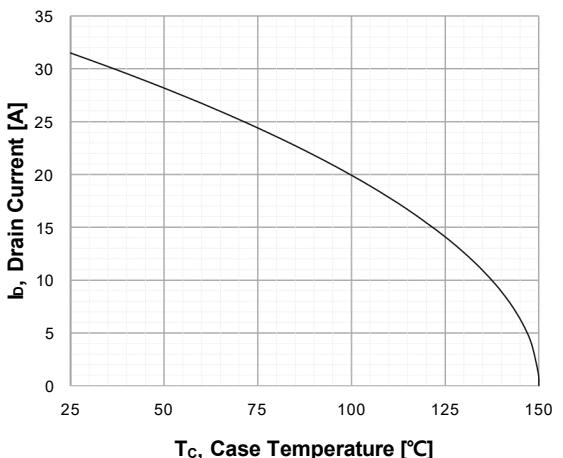
**Figure 8. On-Resistance Characteristics vs. Temperature**



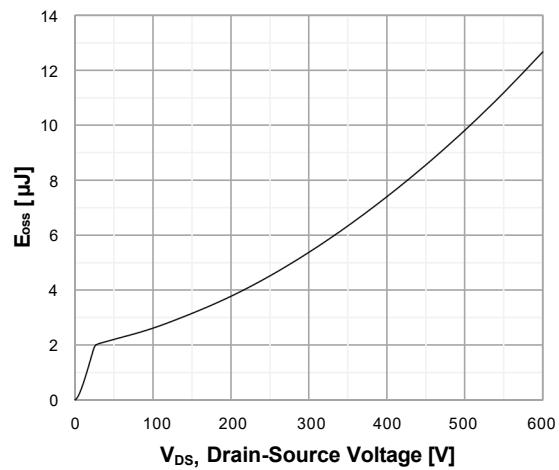
**Figure 9. Maximum Safe Operating Area**



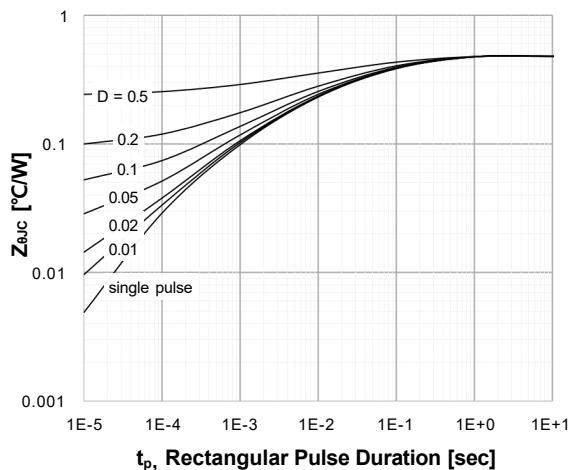
**Figure 10. Maximum Drain Current vs. Case Temperature**



**Figure 11.  $E_{oss}$  vs. Drain to Source Voltage**

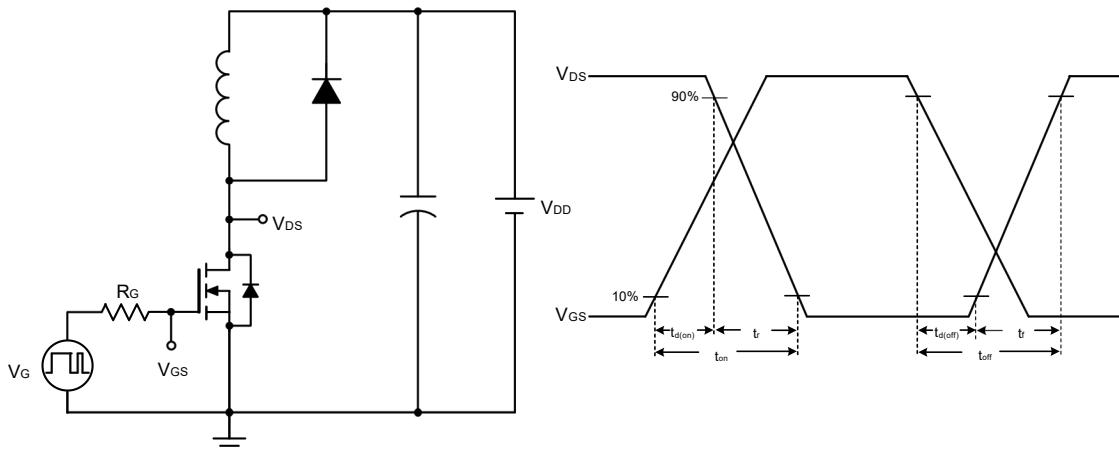


**Figure 12. Transient Thermal Response Curve**

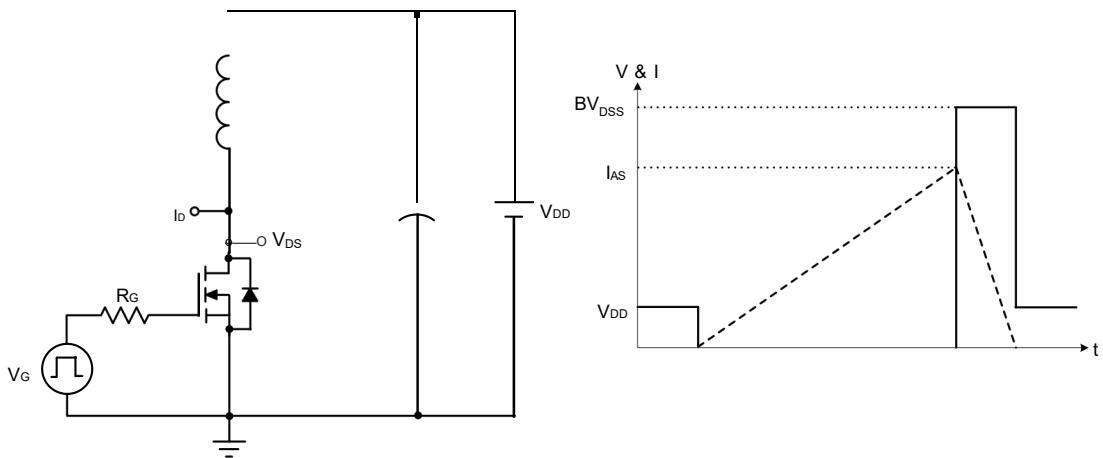


## Test Circuits

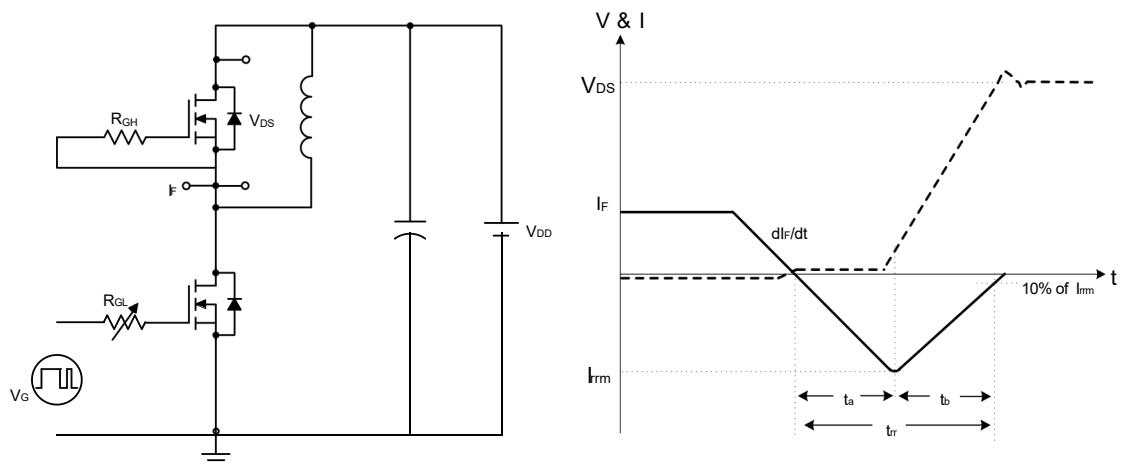
**Figure 13. Inductive Load Switching Test Circuit and Waveforms**



**Figure 14. Unclamped Inductive Switching Test Circuit and Waveforms**

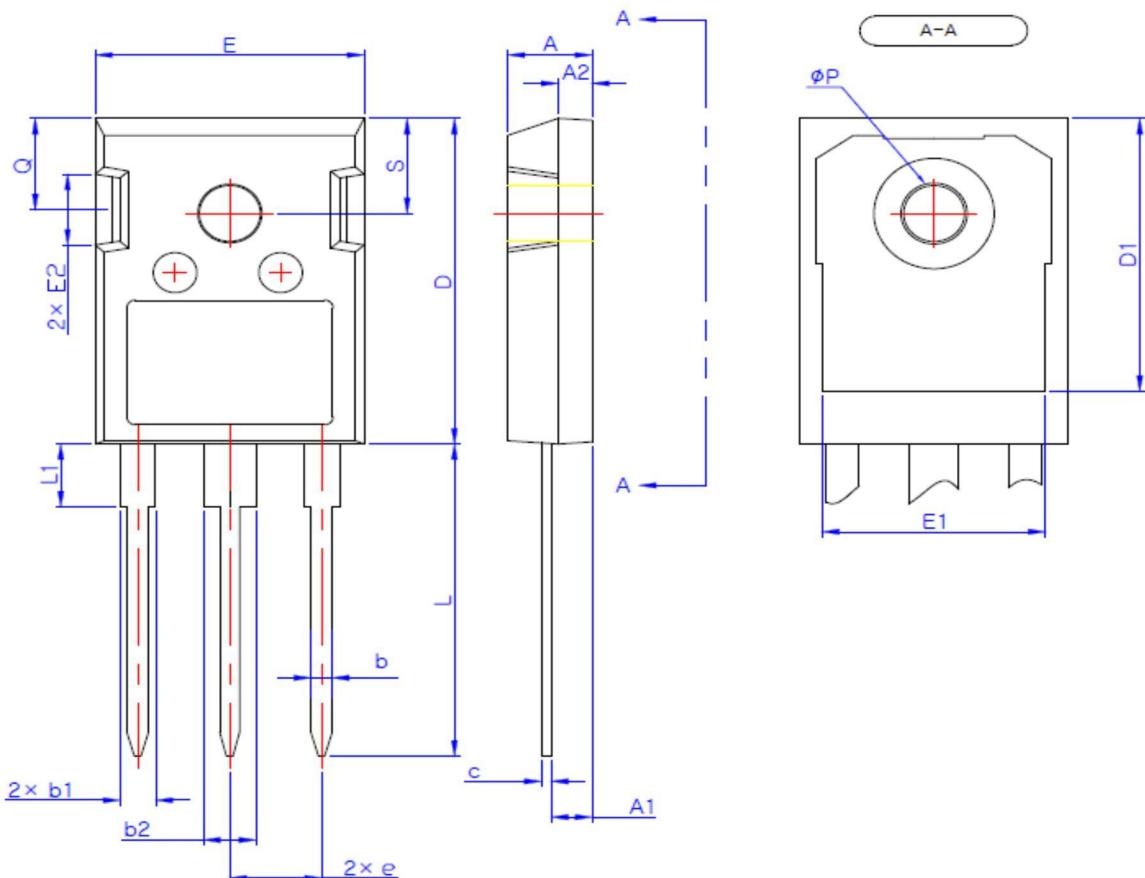


**Figure 15. Peak Diode Recovery dv/dt Test Circuit and Waveforms**



## Package Outlines

## TO-247



SYMBOL	MIN	NOM	MAX
A	4.80	5.00	5.20
A1	2.29	2.42	2.54
A2	1.90	2.00	2.10
b	1.10	1.20	1.30
b1	1.91	2.06	2.20
b2	2.92	3.06	3.20
c	0.50	0.60	0.70
D	20.80	21.07	21.34
D1	17.43	17.63	17.83
E	15.75	15.94	16.13
E1	13.06	13.26	13.46
E2	4.32	4.58	4.83
e	5.45 BSC		
L	19.85	20.05	20.25
L1	4.05	4.27	4.49
$\phi P$	3.55	3.60	3.65
Q	5.59	5.89	6.19
S	6.15 BSC		

\* Dimensions in millimeters